## 12.5-15.5 GHz 21dBm MMIC

## FEATURES

- $\mathrm{P}_{-1} \mathrm{~dB}: 21 \mathrm{dBm}$
- Small Signal Gain: 15 dB
- IP3: 30 dBm
- Bias Condition: $100 \mathrm{~mA} @ 8 \mathrm{~V}$


## PHOTO ENLARGEMENT



## DESCRIPTION

The TC1931D is a two stages PHEMT medium power amplifier MMIC that operates from 12.5 to 15.5 GHz . The amplifier provides a minimum of 15 dB gain and delivers 21 dBm of P1dB. The MMIC is fabricated using Transcom's proprietary matured GaAs PHEMT process. The process features full passivation for increased performance and reliability. All devices are $100 \%$ DC tested to assure consistent quality. Bond pads are gold plated for either thermocompression or thermosonic wire bonding. Backside gold plating is compatible with standard AuSn die-attach.

## ELECTRICAL SPECIFICATIONS ( $\mathbf{T a}=\mathbf{2 5}^{\circ} \mathrm{C}$ )

| SYMBOL | DESCRIPTION | MIN | TYP | MAX | UNITS |
| :--- | :--- | :---: | :---: | :---: | :---: |
| FREQ | Frequency Range | 12.5 |  | 15.5 | GHz |
| SSG | Small Signal Gain @ 15 GHz | 15 | 16 | dB |  |
| P1 dB | Output Power at 1 dB Gain Compression | 20 | 21 | dBm |  |
| P3 dB | Output Power at 3 dB Gain Compression | 21 | 22 | dBm |  |
| IP3 | Third Order Intercept Point | 29 | 30 |  | dBm |
| VSWR, IN | Input VSWR |  | $2: 1$ |  |  |
| VSWR, OUT | Output VSWR |  | $2: 1$ |  |  |
| VDD | Supply Voltage |  | 8 |  |  |
| Vg | Gate Voltage | -0.5 | -1.0 | -1.5 | Volt |
| IDD | Bias Current |  | 100 |  | l |

## ABSOLUTE MAXIMUM RATINGS at $25^{\circ} \mathrm{C}$

| Symbol | Parameter | Rating |
| :---: | :--- | :---: |
| $\mathrm{V}_{\mathrm{DS}}$ | Drain-Source Voltage | 10 V |
| $\mathrm{~V}_{\mathrm{GS}}$ | Gate-Source Voltage | -5 V |
| $\mathrm{I}_{\mathrm{D}}$ | Drain Current | 200 mA |
| $\mathrm{P}_{\mathrm{T}}$ | Continuous Dissipation | 2 W |
| $\mathrm{P}_{\mathrm{in}}$ | Input Power, CW | 10 dBm |
| $\mathrm{T}_{\mathrm{CH}}$ | Channel Temperature | $175^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{STG}}$ | Storage Temperature | $-65^{\circ} \mathrm{C}$ to $+175^{\circ} \mathrm{C}$ |




## MECHANICAL OUTLINE

Units: micrometer (inch)
Thickness: 76.2 (0.003)
Chip Size: $\pm 58$ (0.002)


## ASSEMBLY DIAGRAM



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